

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	24	generat\$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:43
L2	0	L1 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:43
L3	0	L1 and(pre adj treatment or pre-treatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:44
L4	0	L1 and inspect\$3 and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:44
L5	0	L1 and(performing or obtaining)same (pre adj treatment or pre-treatment) and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:45
L6	9	L1 and integrat\$3 and wafer\$1 adj defect\$3 and generat\$3 and distribut \$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:45
L7	9	L6 and(@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:46
L8	9	L7 and(generat\$3 or obtaining)and (drawing or sketch\$3 or geometric) and(image\$1 or file)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:46
L9	0	L8 and inspect\$3 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:47
L10	0	L8 and inspect\$3 and drawings adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:47

L11	9	L8 and integrat\$3 and wafer\$1 adj defect\$3 and generat\$3 and distribut \$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:48
L12	8	L11 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:48
L13	51	generat\$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:52
L14	13	L13 and server and integrat\$4 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:53
L15	11	L14 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:53
L16	2	L15 and(plurality or plural\$1)and stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:54
L17	1983	382/141,145,149,152,147.CCLS.	USPAT	OR	ON	2008/05/26 16:56
L18	5	L17 and generat\$3 and files and wafer adj defect same position and size and type	USPAT	OR	ON	2008/05/26 16:57
L19	0	L18 and server and integrat\$4 and wafer\$1 adj defect\$3	USPAT	OR	ON	2008/05/26 16:57
L20	0	L18 and(plurality or plural\$1)and stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 16:57
L21	5	L18 and @ad<"20040909"	USPAT	OR	ON	2008/05/26 16:58
L22	1902	700/121,110,109.CCLS.	USPAT	OR	ON	2008/05/26 17:00
L23	1012	702/30,122,35.CCLS.	USPAT	OR	ON	2008/05/26 17:01
L24	794	348/126,86,125,92.CCLS.	USPAT	OR	ON	2008/05/26 17:01
L25	4	L22 and generat\$3 and files and wafer adj defect same position and size and type	USPAT	OR	ON	2008/05/26 17:02
L26	1	L25 and server and integrat\$4 and wafer\$1 adj defect\$3	USPAT	OR	ON	2008/05/26 17:02

L27	1	L26 and(plurality or plural\$1)and stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 17:02
L28	1	L27 and(generat\$3 or obtaining)and (drawing or sketch\$3 or geometric) and(image\$1 or file)	USPAT	OR	ON	2008/05/26 17:03
L29	1	L28 and @ad<"20040909"	USPAT	OR	ON	2008/05/26 17:03
L30	0	L29 and(pre adj treatment or pre-treatment or pretreatment)	USPAT	OR	ON	2008/05/26 17:04
L31	124036	inspect\$3 and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or chip adj grid or matrix)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 17:05
L32	292	L31 and generat\$3 same wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 17:05
L33	215	L32 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 17:05
L34	2	L33 and integrat\$3 and wafer\$1 adj defect\$3 and generat\$3 and distribut \$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/26 17:05
L35	0	L34 and drawings adj files	USPAT	OR	ON	2008/05/26 17:05
L36	0	L29 and drawings adj files	USPAT	OR	ON	2008/05/26 17:06
L37	2	L23 and generat\$3 and files and wafer adj defect same position and size and type	USPAT	OR	ON	2008/05/26 17:06
L38	1	L37 and server and integrat\$4 and wafer\$1 adj defect\$3	USPAT	OR	ON	2008/05/26 17:07
L39	3	L24 and generat\$3 and files and wafer adj defect same position and size and type	USPAT	OR	ON	2008/05/26 17:08
L40	0	L39 and server and integrat\$4 and wafer\$1 adj defect\$3	USPAT	OR	ON	2008/05/26 17:08
L41	1	(generat\$3 and files and wafer adj defect and position and size and type and server and integrat\$4 and wafer \$1 adj defect\$3 and(generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and(image\$1 or file)and (pre adj treatment or pre-treatment or pretreatment)).CLM.	US-PGPUB	OR	ON	2008/05/26 17:10

L42	0	L41 and @ad< "20040909"	US-PGPUB	OR	ON	2008/05/26 17:11
S1	2	"6763130".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 11:51
S2	25	inspect\$3 and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 11:59
S3	14	S2 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:18
S5	0	S3 and (pre adj treatment or pre-treatment)and server and integrate same wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:12
S6	0	S3 and (pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:12
S7	0	S3 and server adj integrate with wafer \$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:13
S8	0	S3 and server adj integrate and wafer \$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:17
S9	0	S3 and server adj integrat\$3 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:14
S10	1	S2 and server adj integrat\$3 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:14
S11	1	inspect\$3 and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data and server adj integrat\$3 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:16

S12	3	S2 and server and integrat\$3 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:17
S13	0	S3 and server and integrate and wafer \$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:17
S14	2	S12 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:18
S15	2	S12 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 13:56
S16	2	"7103210".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 13:56
S17	36	inspect\$3 and(wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:23
S18	1	S17 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:25
S19	0	S18 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:25
S20	0	S18 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:25
S21	23	((HUNG-EN) near2 (TAI)).INV.	US-PGPUB; USPAT	OR	ON	2008/05/13 14:26
S22	4	((CHIA-YUN) near2 (CHEN)).INV.	US-PGPUB; USPAT	OR	ON	2008/05/13 14:27
S23	1	S21 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:27

S24	1	S22 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:27
S25	1	S21 and inspect\$3 and(wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:28
S26	1	(performing or obtaining)same(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:29
S27	11	(performing or obtaining)same(pre adj treatment or pre-treatment)and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:30
S28	1	S27 and server and (generat\$3 or obtaining)and drawing adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:32
S29	7	S27 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:33
S30	1	S27 and server and (generat\$3 or obtaining)and(drawing or sketch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:33
S31	0	S29 and server and (generat\$3 or obtaining)and(drawing or sketch\$3 or geometric)and(image\$1 or file)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:34
S32	6	S29 and(generat\$3 or obtaining)and (drawing or sketch\$3 or geometric) and(image\$1 or file)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:34
S33	0	S32 and server	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:35
S34	6	S29 and(generat\$3 or obtaining)and (drawing or sketch\$3 or geometric) and(image\$1 or file)and position and type and size and(display or screen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:37

S35	7	(performing or obtaining) same (pre adj treatment or pre-treatment) and (wafer\$1 or semicondudor\$1 or chip \$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:45
S36	2	S35 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:45
S37	1	server adj integrat\$3 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:47
S38	869	inspect\$3 and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:48
S39	1	S38 and (performing or obtaining) same (pre adj treatment or pre-treatment) and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:49
S40	606	S38 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:49
S41	0	S40 and (performing or obtaining) and (pre adj treatment or pre-treatment) and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:50
S42	0	S40 and (pre adj treatment or pre-treatment) and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:50
S43	8	S40 and (pre adj treatment or pre-treatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:50
S44	0	S43 and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:53

S45	15	manag\$3 and wafer\$1 adj defects and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:54
S46	12	S45 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:54
S47	10	S46 and(generat\$3 or obtaining)and (drawing or sketch\$3 or geometric) and(image\$1 or file)and position and type and size and(display or screen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:55
S48	0	S47 and(pre adj treatment or pre-treatment)and server and integrate and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:56
S49	0	S47 and(pre adj treatment or pre-treatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:56
S50	0	S47 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:57
S51	8	S47 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:58
S52	10	inspect\$3 and wafer\$1 adj defects and server and integrate and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:02
S53	8	S52 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:02
S54	23	S17 and(generat\$3 or obtaining)and (drawing or sketch\$3 or geometric) and(image\$1 or file)and position and type and size and(display or screen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:04
S55	5	S54 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:05

S56	0	S55 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:15
S57	1	S54 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:16
S58	2	generat\$4 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:18
S59	0	S58 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:18
S60	1	S54 and generat\$4 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:19
S61	1	S54 and inspect\$3 and wafer\$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:21
S62	0	S61 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:21
S63	2	inspect\$3 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:21
S64	0	S63 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:22
S65	527773	inspect\$3 drawings adj files and wafer adj defect and(wafer\$1 or semiconduדור\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:23

S66	1	inspect\$3 and drawings adj files and wafer adj defect and(wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board) and generat\$3 adj defect\$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:23
S67	0	chip adj grid and inspect\$3 and (plurality or plural\$1)same inspect\$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:27
S68	29	inspect\$3 and(chip adj grid or wafer \$1 or semicondudor\$1 or chip\$1 or substrat\$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat\$3 adj defect\$3 and (plurality or plural\$1)same stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:31
S69	25	S68 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:31
S70	0	S69 and inspect\$3 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:31
S71	0	S69 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:32
S72	0	S69 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:32
S73	0	S69 and inspect\$3 and wafer\$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:33
S74	0	S69 and wafer\$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:33
S75	0	S69 and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:34

S76	3	S69 and server and integrat\$4 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:34
S77	0	S76 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:44
S78	0	S76 and wafer\$1 adj defects and server and integrat\$4 and wafer\$1 adj defect\$3 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:48
S79	0	S76 and(generat\$3 or obtaining)and distribut\$3 adj data and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:49
S80	0	S76 and(chip adj grid or cells or blocks)and inspect\$3 and(plurality or plural\$1)same inspect\$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:50
S81	606	(chip adj grid or cells or blocks)and inspect\$3 and(plurality or plural\$1) same inspect\$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:51
S82	0	S81 and server and integrat\$4 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:51
S83	2	S81 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:51
S84	0	S83 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:52
S85	0	S68 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:53
S86	29	S68 and generat\$3 adjfiles and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:53

S87	0	S68 and generat\$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:53
S88	0	S68 and generat\$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:54
S89	0	S81 and generat\$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:55
S90	0	S81 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:55
S91	0	S81 and files and wafer adj defect and position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:55
S92	0	S81 and generat\$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
S93	24	generat\$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
S94	51	generat\$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
S95	32	S94 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
S96	11	S95 and server and integrat\$4 and wafer\$1 adj defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:57
S97	0	S96 and(chip adj grid or cells or blocks)and inspect\$3 and(plurality or plural\$1)and inspect\$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:57

S98	0	S96 and(plurality or plural\$1)and inspect\$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:57
S99	2	S96 and(plurality or plural\$1)and stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:58
S100	2	S99 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:58
S101	2	S100 and(subtract\$3 or difference) and defect adj position	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 16:00
S102	1	S100 and(subtract\$3 or difference) and defect adj position and generat\$3 adj data and new adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 16:02
S103	0	S102 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 16:04
S104	2	"6542830".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 09:58
S105	0	S104 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 09:58
S106	0	S104 and drawings adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 09:58
S107	123637	inspect\$3 and (wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or chip adj grid or matrix)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:00
S108	0	S104 and generat\$3 same wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:03

S109	292	S107 and generat\$3 same wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:03
S110	215	S109 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:04
S111	0	S110 and integrat\$3 and wafer\$1 adj defect\$3 same generat\$3 same distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:05
S112	2	S110 and integrat\$3 and wafer\$1 adj defect\$3 and generat\$3 and distribut \$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:05
S113	0	S112 and generat\$3 same drawings adj file and distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:08
S114	0	S112 and generat\$3 and drawings adj file and distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:08
S115	0	S112 and drawings adj file and distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:08
S116	0	S112 and drawings adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:08
S117	2	"7047095".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:17
S118	0	S117 and drawings adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:17
S119	297	generat\$3 same drawings adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:17

S120	13	S119 and inspect\$3 and(wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or chip adj grid or matrix)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:17
S121	5	S120 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:18
S122	0	S121 and integrat\$3 and wafer\$1 adj defect\$3 same generat\$3 same distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:18
S123	0	S121 and integrat\$3 and wafer\$1 adj defect\$3 and generat\$3 and distribut \$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:18
S124	0	S121 and integrat\$3 and wafer\$1 adj defect\$3 and distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:19
S125	0	S121 and wafer\$1 adj defect\$3 and distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:19
S126	0	S121 and distribut\$3 adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:19
S127	5	S121 and inspect\$3 and(wafer\$1 or semicondudor\$1 or chip\$1 or substrat \$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or chip adj grid or matrix or circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/14 10:23

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